

## 256-word × 4-bit parallel NON-VOLATILE RAM

The S-22H12R/I is a non-volatile CMOS RAM, composed of a CMOS static RAM and a non-volatile electrically erasable programmable memory (E<sup>2</sup>PROM) to backup the SRAM.

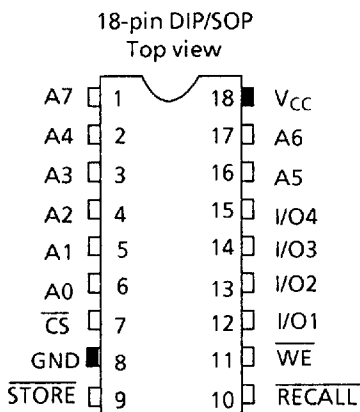
The organization is 256-word × 4-bit (total 1024 bits) and the RAM is asynchronously CMOS static. The pin layout is compatible with X2212 of Xicor Ltd.

When a store signal is input to the SRAM, all the data is copied into the E<sup>2</sup>PROM. When a recall signal is input, the E<sup>2</sup>PROM data is recopied into the SRAM.

### ■ Features

- Low current consumption  
 Operating : 10 mA typ.  
 Standby : 1 μA max.
- All inputs and outputs are compatible with TTL.
- +5-V single power supply (+5 V ± 10%)
- Completely static operation
- Access time: 200 ns max.
- CMOS floating gate process
- Tri-state output
- $\overline{\text{STORE}}$  and  $\overline{\text{RECALL}}$  are controlled by a short pulse width: 200 ns min.
- E<sup>2</sup>PROM store cycles: 10<sup>4</sup>/10<sup>5</sup> times
- E<sup>2</sup>PROM memory retention: 10 years
- Erroneous store protection: ≈ 3.5 V
- 18-pin DIP/SOP

### ■ Pin Arrangement



A0 to A7	Address input
I/O1 to I/O4	Data input/output
$\overline{\text{WE}}$	Write enable
$\overline{\text{CS}}$	Chip select
$\overline{\text{RECALL}}$	Recall
$\overline{\text{STORE}}$	Store
V <sub>CC</sub>	Power supply voltage (+5 V)
GND	Ground (0 V)

Figure 1

# S-22H12R/I

## Block Diagram

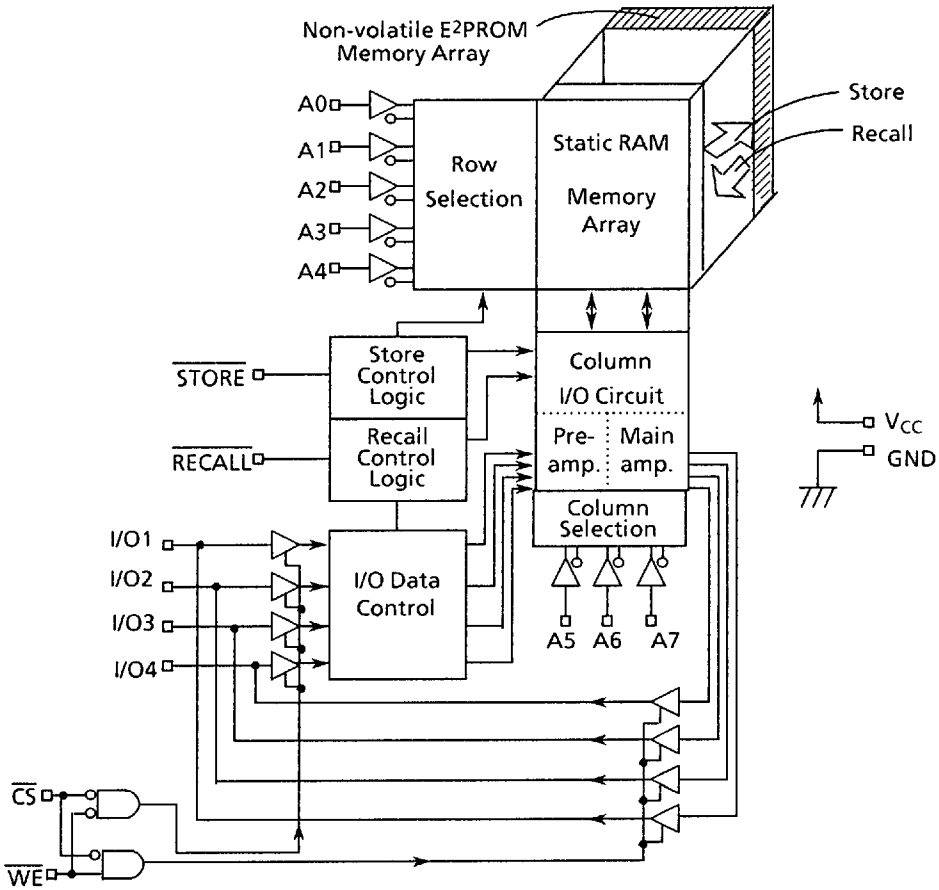


Figure 2

## Absolute Maximum Ratings

Table 1

Item	Symbol	Condition	Ratings	Unit
Storage temperature	$T_{stg}$	S-22H12R	-65 to +125	°C
		S-22H12I	-65 to +150	°C
Storage temperature under bias	$T_{bias}$	S-22H12R	-10 to +85	°C
		S-22H12I	-50 to +95	°C
Power supply voltage	$V_{CC}$		-0.3 to +6.0	V
Input voltage	$V_{IN}$		-0.3 to $V_{CC} + 0.3$	V
Output voltage	$V_{OUT}$		0.0 to $V_{CC}$	V

## ■ Recommended Operating Conditions

Table 2

Item	Symbol	Conditions	Min.	Typ.	Max.	Unit
Power supply voltage	$V_{CC}$		4.5	5.0	5.5	V
High level input voltage	$V_{IH}$		2.0	—	$V_{CC}$	V
Low level input voltage	$V_{IL}$		0.0	—	0.8	V
Operating temperature	$T_{opr}$	S-22H12R	0	—	+70	°C
		S-22H12I	-40	—	+85	°C

## ■ DC Electrical Characteristics

Table 3

Item	Symbol	Conditions	Min.	Typ.	Max.	Unit
Operating current consumption	$I_{CC}$	S-22H12R	—	10	20	mA
		S-22H12I	—	10	30	mA
Standby current consumption	$I_{SB}$	$\overline{CS} = V_{CC}$ Other inputs are $V_{CC}$ or GND	—	—	1	$\mu A$
Input leakage current	$I_{LI}$	$V_{IN} = \text{GND to } V_{CC}$	—	0.1	1	$\mu A$
Output leakage current	$I_{LO}$	$V_{OUT} = \text{GND to } V_{CC}$	—	0.1	1	$\mu A$
High level output voltage	$V_{OH}$	TTL $I_{OH} = -2 \text{ mA}$	2.4	—	—	V
		CMOS $I_{OH} = -100 \mu A$	$V_{CC}-0.1$	—	—	V
Low level output voltage	$V_{OL}$	TTL $I_{OL} = 4.2 \text{ mA}$	—	—	0.4	V
		CMOS $I_{OL} = 100 \mu A$	—	—	0.1	V
Store inhibition voltage	$V_{WI}$	S-22H12R	—	3.5	4.0	V
		S-22H12I	—	3.5	4.1	V

# S-22H12R/I

## Data Hold Characteristics

Table 4

Item	Symbol	Conditions	Min.	Typ.	Max.	Unit
Data hold voltage	$V_{DH}$	$\overline{CS} \geq V_{CC} - 0.2V, \overline{RECALL} \geq V_{CC} - 0.2V$	1.5	—	5.5	V
Data hold setup time	$t_{CDH}$		50	—	—	ns
Recovery time	$t_R$		300	—	—	ns

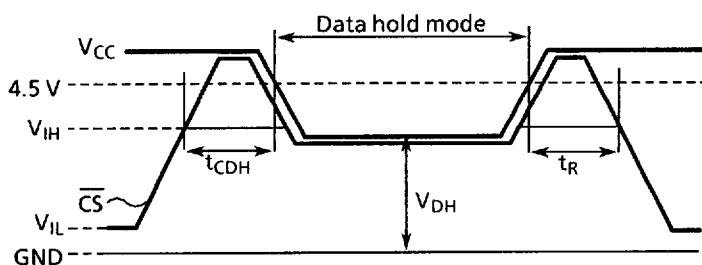


Figure 3

## Capacitance

Table 5

( $T_a = 25^\circ C, f = 1.0 \text{ MHz}, V_{CC} = 5 \text{ V}$ )

Item	Symbol	Conditions	Min.	Typ.	Max.	Unit
Input capacitance	$C_{IN}$	$V_{IN} = 0 \text{ V}$	—	—	6	pF
Output capacitance (I/O pin)	$C_{I/O}$	$V_{I/O} = 0 \text{ V}$	—	—	10	pF

## ■ AC Electrical Characteristics

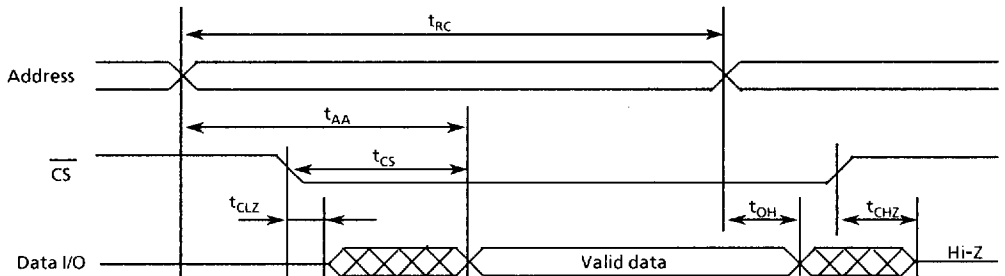
**Table 6 Measurement conditions**

Item	S-22H12R	S-22H12I	Unit
Input pulse voltage	0.65 to 2.2	0.0 to 3.0	V
Input pulse rise/fall time	10	10	ns
I/O reference voltage	1.5	1.5	V
Output load	1TTL + 100pF	1TTL + 100pF	

### 1. Read cycle

**Table 7**

Item	Symbol	Min.	Typ.	Max.	Unit
Read cycle time	$t_{RC}$	200	—	—	ns
Address access time	$t_{AA}$	—	—	200	ns
$\overline{CS}$ access time	$t_{CS}$	—	—	200	ns
Output data hold time	$t_{OH}$	20	—	—	ns
Output enable time ( $\overline{CS}$ )	$t_{CLZ}$	10	—	—	ns
Output disable time ( $\overline{CS}$ )	$t_{CHZ}$	10	—	70	ns



**Figure 4**

## 2. Write cycle

Table 8

Item	Symbol	Min.	Typ.	Max.	Unit
Write cycle time	$t_{WC}$	200	—	—	ns
$\overline{CS}$ pulse width	$t_{CW}$	120	—	—	ns
Address setup time	$t_{AS}$	20	—	—	ns
$\overline{WE}$ pulse width	$t_{WP}$	120	—	—	ns
Write reset time	$t_{WR}$	25	—	—	ns
Input data setup time	$t_{DW}$	50	—	—	ns
Input data hold time	$t_{DH}$	20	—	—	ns
Output disable time ( $\overline{WE}$ )	$t_{WHZ}$	10	—	70	ns
Output enable time ( $\overline{WE}$ )	$t_{WLZ}$	10	—	—	ns

### · Write cycle 1 : $\overline{WE}$ control

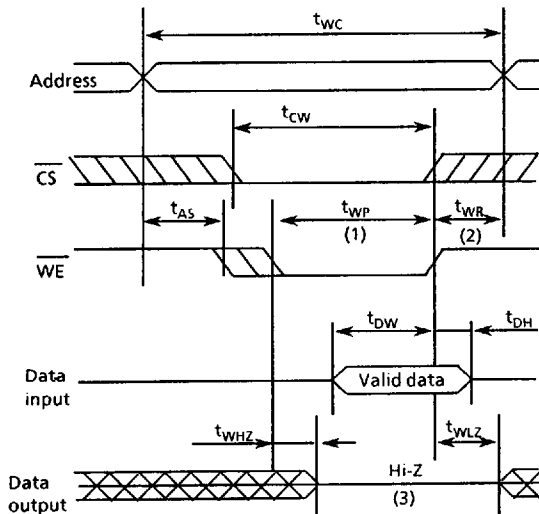


Figure 5

### · Write cycle 2 : $\overline{CS}$ control

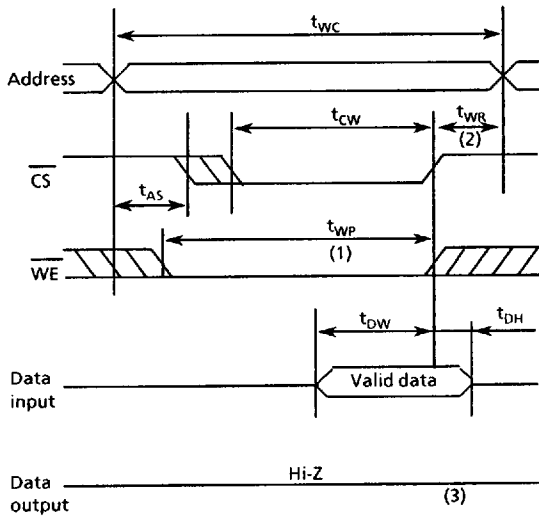


Figure 6

- (1) The write cycle starts when both  $\overline{CS}$  and  $\overline{WE}$  are low.
- (2)  $t_{WR}$  is the period of time from the rise of  $\overline{CS}$  or  $\overline{WE}$  whichever is the first to the end of write cycle.
- (3) Output remains in high-impedance state when  $\overline{CS}$  falls simultaneously with or after the fall of  $\overline{WE}$ .

3. Store cycle

Table 9

Item	Symbol	Min.	Typ.	Max.	Unit
Store time	$t_{ST}$	—	—	10	ms
Store pulse width	$t_{STP}$	200	—	—	ns
Store disable time	$t_{STZ}$	—	—	100	ns
Store enable time	$t_{OST}$	10	—	—	ns

Store operation starts at the falling of  $\overline{\text{STORE}}$ .

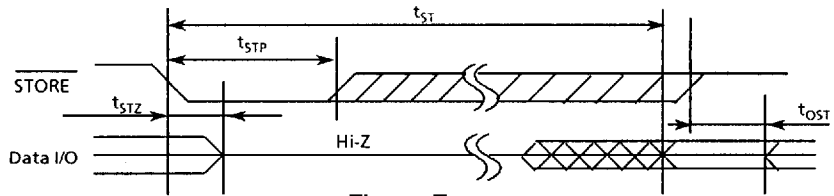


Figure 7

4. Recall cycle

Table 10

Item	Symbol	Min.	Typ.	Max.	Unit
Recall cycle time	$t_{RCC}$	1300	1000	—	ns
Recall pulse width	$t_{RCP}$	200	—	—	ns
Recall disable time	$t_{RCZ}$	—	—	100	ns
Recall enable time	$t_{ORC}$	10	—	—	ns
Recall data access time	$t_{ARC}$	—	—	1100	ns

Recall operation starts at the rise of  $\overline{\text{RECALL}}$ .  
It can be repeated without limitation.

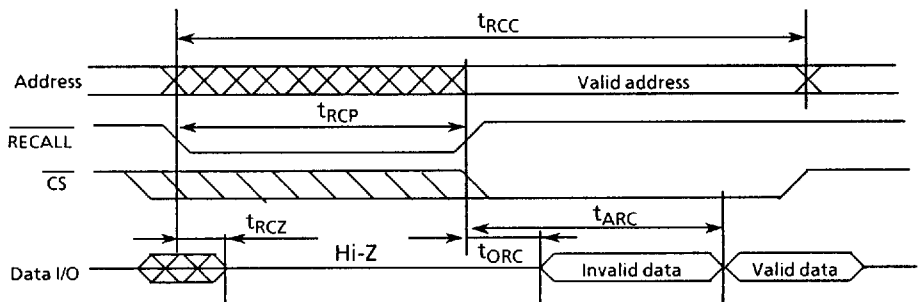


Figure 8

# S-22H12R/I

## ■ Operation Mode

Table 11

Mode	Input				Input/Output
	$\overline{CS}$	$\overline{WE}$	$\overline{RECALL}$	$\overline{STORE}$	
Standby mode	H	X	H	H	Output is high impedance
Read mode	L	H	H	H	Output data
Write mode	L	L	H	H	Input data
Recall mode	X	H	L	H	Output is high impedance
	H	X	L	H	
Store mode	X	H	H	L	Output is high impedance
	H	X	H	L	

X : don't care

- Notes:
- When  $\overline{RECALL}$  and  $\overline{STORE}$  are simultaneously input,  $\overline{RECALL}$  is valid.
  - When  $\overline{RECALL}$  is low,  $\overline{STORE}$  cannot be received.
  - When power supply voltage ( $V_{CC}$ ) is below store inhibition voltage  $V_{WI}$ , the store operation is inhibited.

## ■ Operation

### 1. Standby mode

When  $\overline{CS}$  goes high, the S-22H12R/I enters into the standby mode: power consumption becomes lowest, and I/O1 to I/O4 are high impedance.

### 2. SRAM modes

#### 2.1 Read mode

When  $\overline{CS}$  is low and  $\overline{WE}$  is high, the S-22H12R/I enters into the read mode: the SRAM data is output to I/O1 to I/O4.

#### 2.2 Write mode

When  $\overline{CS}$  and  $\overline{WE}$  are low, the S-22H12R/I enters into the write mode: the data input in I/O1 to I/O4 is written to the SRAM.

### 3. SRAM↔E<sup>2</sup>PROM mode

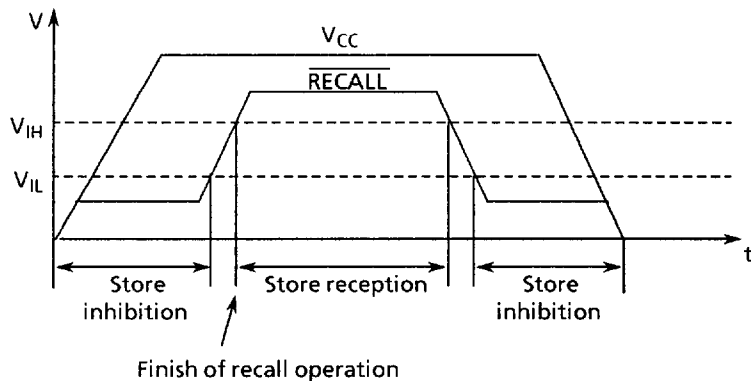
#### 3.1 Store mode

When  $\overline{\text{STORE}}$  goes low, the S-22H12R/I enters into the store mode: the SRAM data is copied to the E<sup>2</sup>PROM. The original data in the SRAM is effective. Since the copied data in the E<sup>2</sup>PROM is non-volatile, they are retained even if power turns off. When  $\overline{\text{STORE}}$  falls, the store operation starts and finishes automatically. When store operation starts, I/O1 to I/O4 go to high impedance and other operations are inhibited until store operation is finished and  $\overline{\text{STORE}}$  goes to high. During store operation, the CPU can access other instructions.

The store operation is inhibited if power supply voltage ( $V_{CC}$ ) is under  $V_{WI}$  ( $\approx 3.5$  V.)

The following two methods prevent erroneous store, caused by noise when power turns on or off:

- $\overline{\text{RECALL}}$  goes low when power turns on or off (see Figure 9).
- $\overline{\text{STORE}}$  connects to  $V_{CC}$  with pull-up resistor.



**Figure 9 STORE inhibition period and reception period at power ON and OFF**

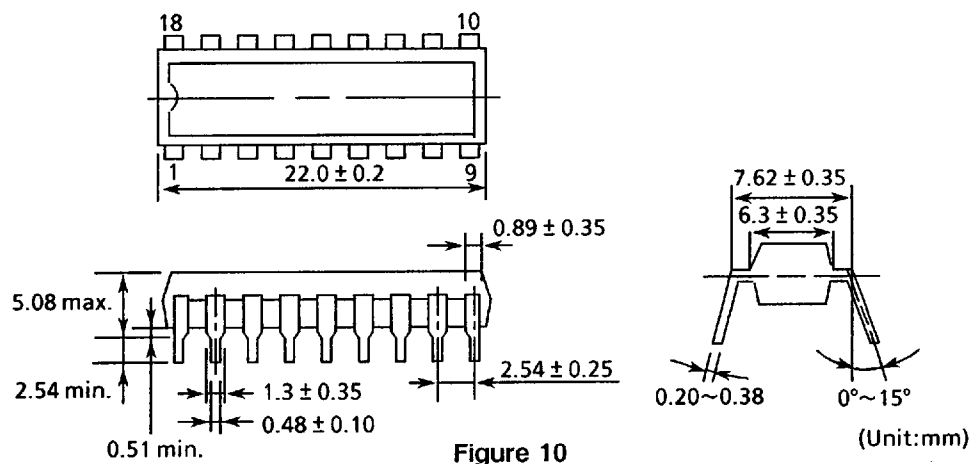
#### 3.2 Recall mode

When  $\overline{\text{RECALL}}$  goes low, the S-22H12R/I enters into the recall mode: the data copied into the E<sup>2</sup>PROM is recopied to the SRAM. The recopied data can be read or written as SRAM data. Even if the data is copied repeatedly, the data in the E<sup>2</sup>PROM does not change. Other operations are inhibited during its operation.

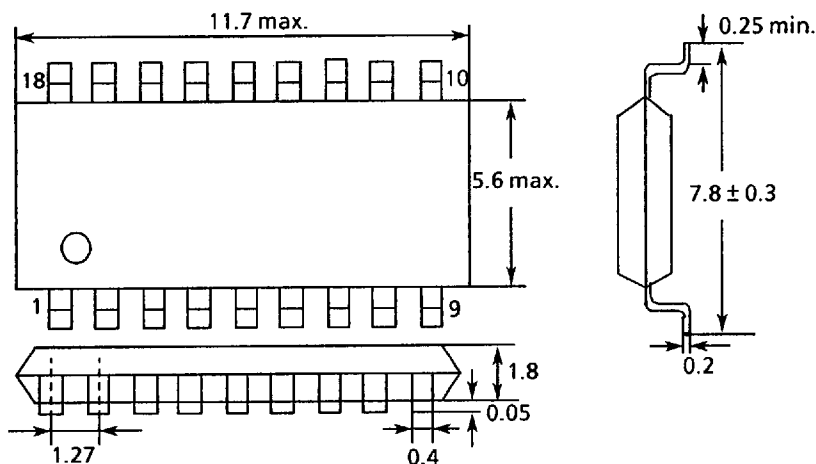
# S-22H12R/I

## ■ Dimensions

### 1. S-22H12R/I (18-pin DIP)



### 2. S-22H12RF/IF (18-pin SOP)



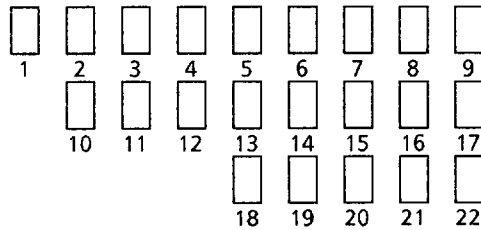
## ■ Ordering Information

Table 12

Product name	Store cycles	Store cycles per bit	Temperature	Package
S-22H12R 01/10	10 <sup>4</sup> /10 <sup>5</sup>	10 <sup>4</sup> /10 <sup>5</sup>	0°C to +70°C	Plastic DIP
S-22H12I 01/10	10 <sup>4</sup> /10 <sup>5</sup>	10 <sup>4</sup> /10 <sup>5</sup>	-40°C to +85°C	Plastic DIP
S-22H12RF 01/10	10 <sup>4</sup> /10 <sup>5</sup>	10 <sup>4</sup> /10 <sup>5</sup>	0°C to +70°C	Plastic SOP
S-22H12IF 01/10	10 <sup>4</sup> /10 <sup>5</sup>	10 <sup>4</sup> /10 <sup>5</sup>	-40°C to +85°C	Plastic SOP

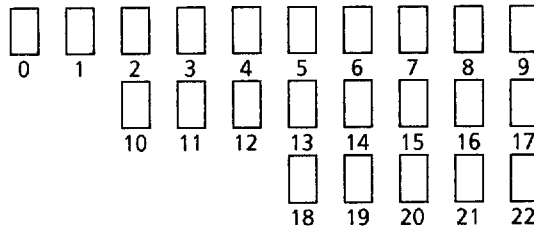
## ■ Markings

### 1. S-22H12R/I (18-pin DIP)



- 1 to 9 : Product name
- 10 : Assembly code
- 11 : Year of manufacturing (last digit)
- 12 : Month of manufacturing : January = 1, February = 2,  
March = 3, April = 4, May = 5, June = 6, July = 7, August = 8,  
September = 9, October = X, November = Y, December = Z
- 13 to 17 : Lot No.
- 18 to 22 : 『 JAPAN 』

### 2. S-22H12RF/IF (18-pin SOP)



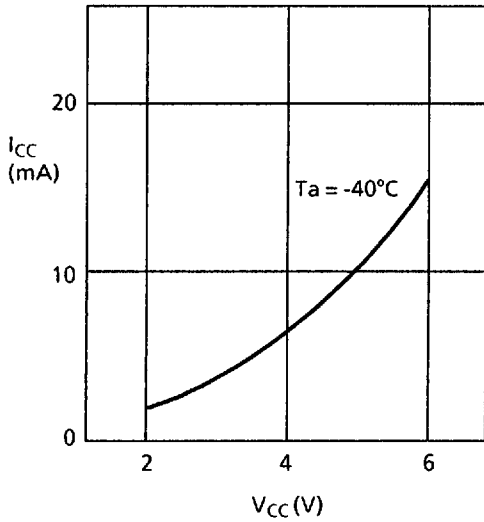
- 0 to 9 : Product name
- 10 : Assembly code
- 11 : Year of manufacturing (last digit)
- 12 : Month of manufacturing : January = 1, February = 2,  
March = 3, April = 4, May = 5, June = 6, July = 7, August = 8,  
September = 9, October = X, November = Y, December = Z
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# S-22H12R/I

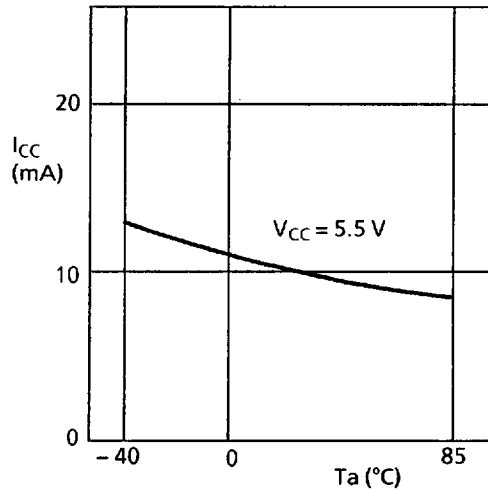
## ■ Characteristics

### 1. DC characteristics

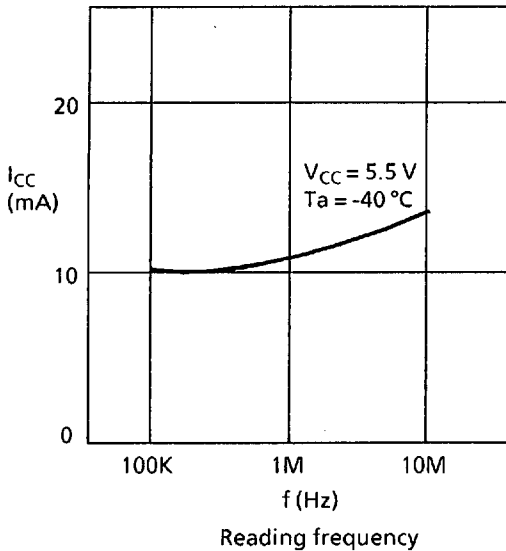
1.1 Operating current consumption  $I_{CC}$   
— Power supply voltage  $V_{CC}$



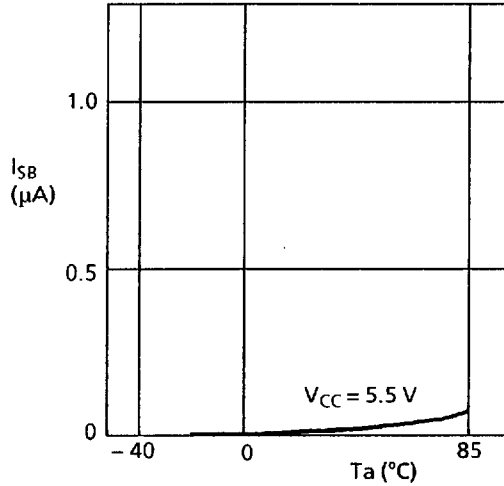
1.2 Operating current consumption  $I_{CC}$   
— Ambient temperature  $T_a$



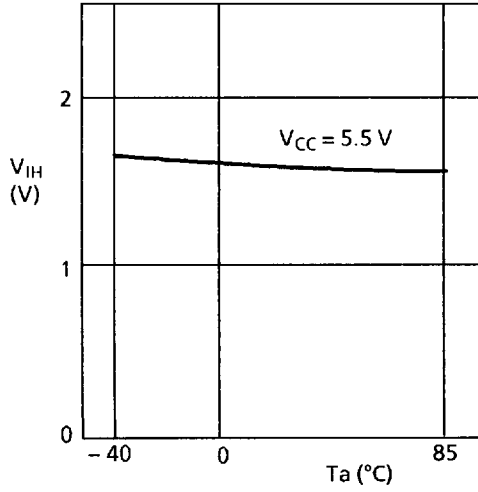
1.3 Operating current consumption  $I_{CC}$   
— Reading frequency



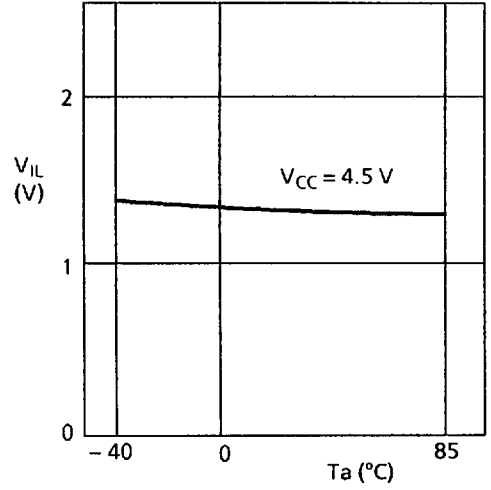
1.4 Standby current consumption  $I_{SB}$   
— Ambient temperature  $T_a$



1.5 High level input voltage  $V_{IH}$  — Ambient temperature  $T_a$



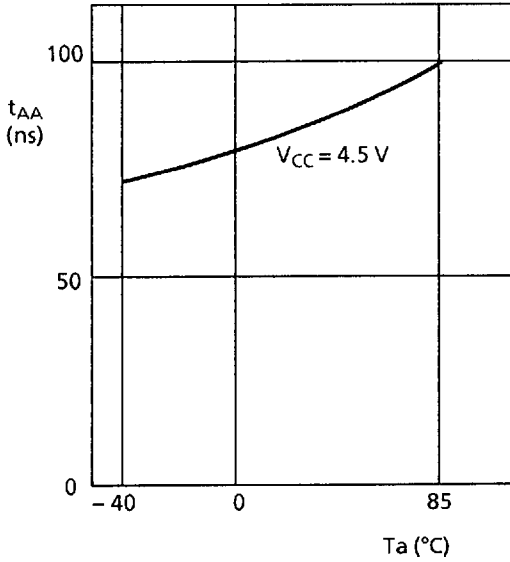
1.6 Low level input voltage  $V_{IL}$  — Ambient temperature  $T_a$



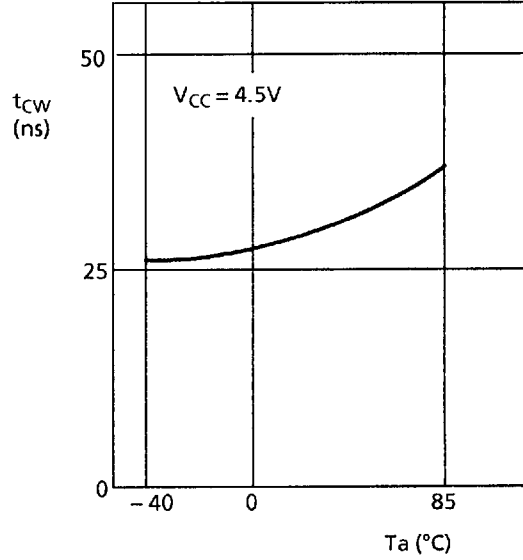
# S-22H12R/I

## 2. AC Characteristics

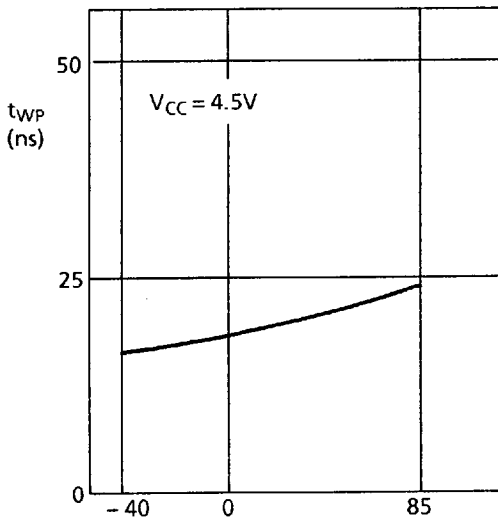
2.1 Address access time  $t_{AA}$  — Ambient temperature  $T_a$



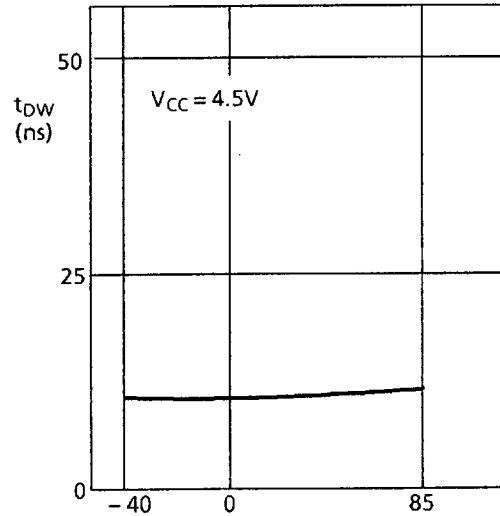
2.2  $\overline{CS}$  pulse width  $t_{CW}$  — Ambient temperature  $T_a$



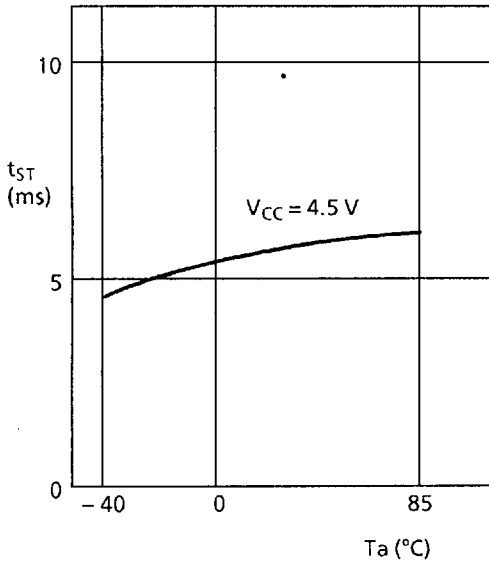
2.3  $\overline{WE}$  pulse width  $t_{WP}$  — Ambient temperature  $T_a$



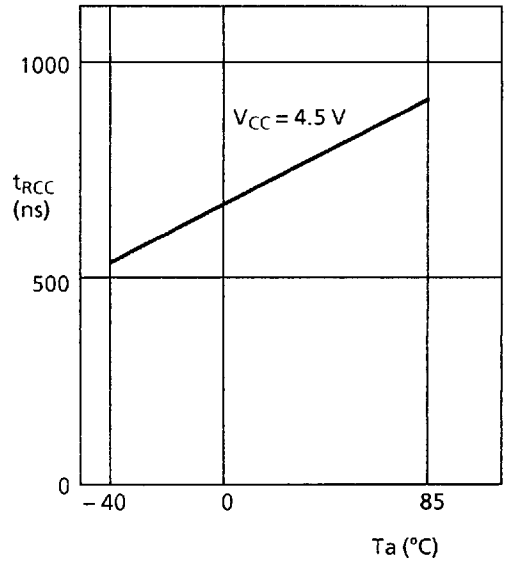
2.4 Input data setup time  $t_{DW}$  — Ambient temperature  $T_a$



2.5 Store time  $t_{ST}$  — Ambient temperature  $T_a$



2.6 Recall cycle time  $t_{RCC}$  — Ambient temperature  $T_a$



### 3. Store Characteristic

